

PATENTS ONLY

03-02-2005



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<p>1. Name of party or parties conveying an interest:</p> <p>Jae-Suk LEE</p>	<p>2. Name and address of party or parties receiving an interest:</p> <p>Name: Donbu Electronics Co., Ltd. 838, Yeoksam 1-dong, Kangnam-ku Seoul, 135-080, Korea</p>
<p>3. Description of the interest conveyed:</p> <p><input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Change of Name <input type="checkbox"/> Security Agreement</p> <p>Execution Date: July 22, 2004</p>	<p>Other:</p> <p style="text-align: right;">OFFICE OF PUBLIC RECORDS 2005 FEB 24 PM 12:10 FINANCE SECTION</p>
<p>4. Application number(s) or patent number(s). Additional sheet attached? YES ___ NO <u>X</u></p> <p>A. Patent Application no.(s): 10/902,903 filed July 30, 2004</p>	<p>If the document is being filed together with a new application, the execution date of the application is:</p> <p>B. Patent no.(s):</p>
<p>5. Name and address of party to whom correspondence concerning this cover sheet should be mailed:</p> <p>Name: Mark G. Hanley Reg. No. 44,736 HANLEY, FLIGHT & ZIMMERMAN, LLC Street Address: 20 North Wacker Drive Suite 4220 City: Chicago State: Illinois Zip: 60606</p>	<p>6. Number of applications and/or patents identified on this cover sheet: 1</p> <p>7. Amount of fee enclosed or authorized to be charged: \$40.00</p> <p>8. Any additional required fee may be charged, or any overpayment credited to our deposit account: 50-2455</p>

S-O-P-E-C

9. To the best of my knowledge and belief, the information contained on this cover sheet is true and correct and any copy submitted is a true copy of the original document.

Date: February 17, 2005

Mark G. Hanley
Registration No. 44,736

Total number of pages including cover sheet, attachments, and document: 11

03/01/2005 6TOM11 00000147 10902903
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11696 U.S. PTO
073004

08-06-2004

PATENT APPLICATION

IN THE UNIT



EMARK OFFICE

102807832

set No: 20067/OPP041612US

PATENT APPLICATION TRANSMITTAL UNDER 37 C.F.R. 1.53

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

22141 U.S. PTO
10/902903
073004

Sir: 7-30-04

Transmitted herewith for filing is the patent application of

Inventor: Jae-Suk LEE

Title: "Method for Fabricating Metal Wiring and Semiconductor Device Having the Same"

1. Type of Application

- This is a new application for a
- utility patent.

2. Application Papers Enclosed

- 1 Title Page
- 6 Pages of Specification
(excluding Claims, Abstract, Sequence Listing & Drawings)
- 2 Pages of Claims
- 1 Page of Abstract
- 2 Sheets of Drawings (FIGS. 1 to 2C)
- Formal
- Informal

CERTIFICATION UNDER 37 CFR 1.10

I hereby certify that this Patent Application Transmittal and the documents referred to as enclosed therewith are being deposited with the United States Postal Service on July 30, 2004 in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 utilizing the "Express Mail Post Office to Addressee" service of the United States Postal Service under Mailing Label No. EV532856811 US.

Sarah Southcott

08/03/2004 5ZEWDIE1 00000022 10902903
40.00 DP

3. Declaration or Oath

- Enclosed
- Executed by (check all applicable boxes)
- Inventor(s)
- Legal representative of inventor(s)
(37 CFR 1.42 or 1.43)
- Joint inventor or person showing a proprietary interest on behalf of inventor who refused to sign or cannot be reached.
- The petition required by 37 CFR 1.47 and the statement required by 37 CFR 1.47 are enclosed.
See Item 5D below for fee.
- Not enclosed - the undersigned attorney or agent is authorized to file this application on behalf of the applicant(s). An executed declaration will follow.

4. Small Entity Status

- Applicant claims small entity status. See 37 CFR 1.27.
- A small entity statement is(are) attached.

5. Additional Papers Enclosed

- Preliminary Amendment
- Information Disclosure Statement
- Declaration of Biological Deposit
- Computer readable copy of sequence listing containing nucleotide and/or amino acid sequence
- Microfiche computer program
- Associate Power of Attorney
- Verified translation of a non-English patent application
- An assignment of the invention
- Request and Certification Under 35 U.S.C. 122(b)(2)(B)(i)
- Return receipt postcard
- Other

6. Priority Applications Under 35 USC 119

Certified copies of applications from which priority under 35 USC 119 is claimed are listed below and

- are attached.
 will follow.

COUNTRY	APPLICATION NO.	FILED
Korea	10-2003-0053016	July 31, 2003

7. Filing Fee Calculation (37 CFR 1.16)

A. Utility Application

CLAIMS AS FILED - INCLUDING PRELIMINARY AMENDMENT(S) (IF ANY)						
			SMALL ENTITY		OTHER THAN A SMALL ENTITY	
	NO. FILED	NO. EXTRA	RATE	FEE	RATE	FEE
BASIC FEE				\$385.00		\$770.00
TOTAL	9 - 20	= 0	X 9 =	\$	X 18 =	\$0.00
INDEP.	2 - 3	= 0	X 43 =	\$	X 86 =	\$0.00
First Presentation of Multiple Dependent Claim			+ 145 =	\$	+ 290 =	\$
Filing Fee:				\$	OR	\$770.00

B. Design Application (\$170.00/\$340.00) Filing Fee: \$0.00

C. Plant Application (\$265.00/\$530.00) Filing Fee: \$0.00

D. Other Fees

Recording Assignment [Fee — \$40.00 per assignment] \$40.00

Petition fee for filing by other than all the inventors or person on behalf of the inventor where inventor refused to sign or cannot be reached [Fee — \$130.00] \$0.00

Other \$0.00

Total Fees Enclosed \$810.00

8. Method of Payment of Fees

- Enclosed check in the amount of: \$810.00
- Charge Deposit Account No. 50-2455 in the amount of: \$0.00
A copy of this Transmittal is enclosed.
- Not enclosed

9. Deposit Account and Refund Authorization

The Commissioner is hereby authorized to charge any deficiency in the amount enclosed or any additional fees which may be required during the pendency of this application under 37 CFR 1.16 or 37 CFR 1.17 or under other applicable rules (except payment of issue fees), to Deposit Account No. 50-2455. A copy of this Transmittal is enclosed.

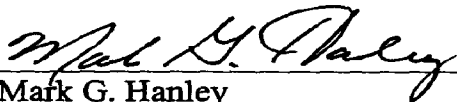
Please refund any overpayment to Grossman & Flight LLC at the address below.

10. Correspondence Address

Respectfully submitted,

GROSSMAN & FLIGHT LLC
20 North Wacker Drive
Suite 4220
Chicago, Illinois 60606-6357
(312) 580-1020
(312) 580-9696 (Telefacsimile)

By:



Mark G. Hanley
Registration No.: 44,736

July 30, 2004

ASSIGNMENT

Serial No: 10/902,903
Filed: July 30, 2004
Title: METHOD FOR FABRICATING METAL WIRING AND SEMICONDUCTOR DEVICE HAVING THE SAME

For good and valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assigns to DONGBU ELECTRONICS CO., LTD. of 838, Yeoksam 1-dong, Kangnam-ku, Seoul, 135-080, Korea, (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, and in said application and any and all other applications, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States, which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

The undersigned hereby authorizes and requests the attorneys of record in said application to insert in this assignment the execution date and/or filing date and serial number of said application when officially known.

The undersigned warrants himself to be the owner of the interest herein assigned and to have the right to make this assignment and further warrants that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned.

For said consideration the undersigned hereby agrees, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation, continuation-in-part and substitute applications for said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application, that said assignee, its successors or assigns, may deem necessary or expedient, and for said consideration the undersigned further agrees upon the request of said assignee, its successors or assigns, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned with said assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said Letters Patent, and vest all rights therein hereby conveyed in said assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by said assignee, its successors and assigns, to the full end of

the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

Date: July 22, 2004

Signature

Lee Jae Suk

Name

LEE, Jae-Suk

* * * * *

ASSIGNMENT

Serial No:

Filed: July 30, 2004
Title: METHOD FOR FABRICATING METAL WIRING AND
SEMICONDUCTOR DEVICE HAVING THE SAME

For good and valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assigns to DONGBU ELECTRONICS CO., LTD. of 838, Yeoksam 1-dong, Kangnam-ku, Seoul, 135-080, Korea, (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, and in said application and any and all other applications, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States, which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

The undersigned hereby authorizes and requests the attorneys of record in said application to insert in this assignment the execution date and/or filing date and serial number of said application when officially known.

The undersigned warrants himself to be the owner of the interest herein assigned and to have the right to make this assignment and further warrants that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned.

For said consideration the undersigned hereby agrees, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation, continuation-in-part and substitute applications for said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application, that said assignee, its successors or assigns, may deem necessary or expedient, and for said consideration the undersigned further agrees upon the request of said assignee, its successors or assigns, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned with said assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said Letters Patent, and vest all rights therein hereby conveyed in said assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by said assignee, its successors and assigns, to the full end of

the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

Date: July 22, 2004

Signature

Lee Jae Suk

Name

LEE, Jae-Suk

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